

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0003] as follows:

[0003] Generally, the various process steps required for manufacturing semiconductor devices are broadly grouped into the fabrication steps required to form semiconductor chips on a semiconductor wafer, the packaging steps required to separate the individual semiconductor chips and mount the chip or chips in a package and the testing steps required for confirming the functionality of the completed semiconductor package. The packaging steps include steps for sawing the semiconductor wafer to divide the semiconductor elements formed in the wafer into individual chips, attaching the individual chips to die pads provided on a series of leadframes, wire-bonding to ~~from~~ form electrical connections between the chip bonding pads and the leadframe inner leads, encapsulating the individual chips with a molding compound, plating the outer leadframe leads with solder and bending, cutting or otherwise forming the plated outer leads into the desired configuration to form discrete packages.

Please amend paragraph [0031] as follows:

[0031] As illustrated in FIGS. 7-10, the protective tape 206 is adhered to the upper surface of the wafer 204 to protect the circuit area of the chips formed on the upper surface of the wafer. A backside grinding process is then performed to thin wafer ~~203~~ 204, after which the thinned wafer is fixed to a jig 202 or other wafer carrier assembly by the adhesive tape 200 or by vacuum applied to the backside of the wafer (not shown). The fixed wafer 204 is then transferred to a wafer sawing station (as generally illustrated in FIG. 2) by a transfer mechanism or combination of mechanisms (not shown).